

Fig.1

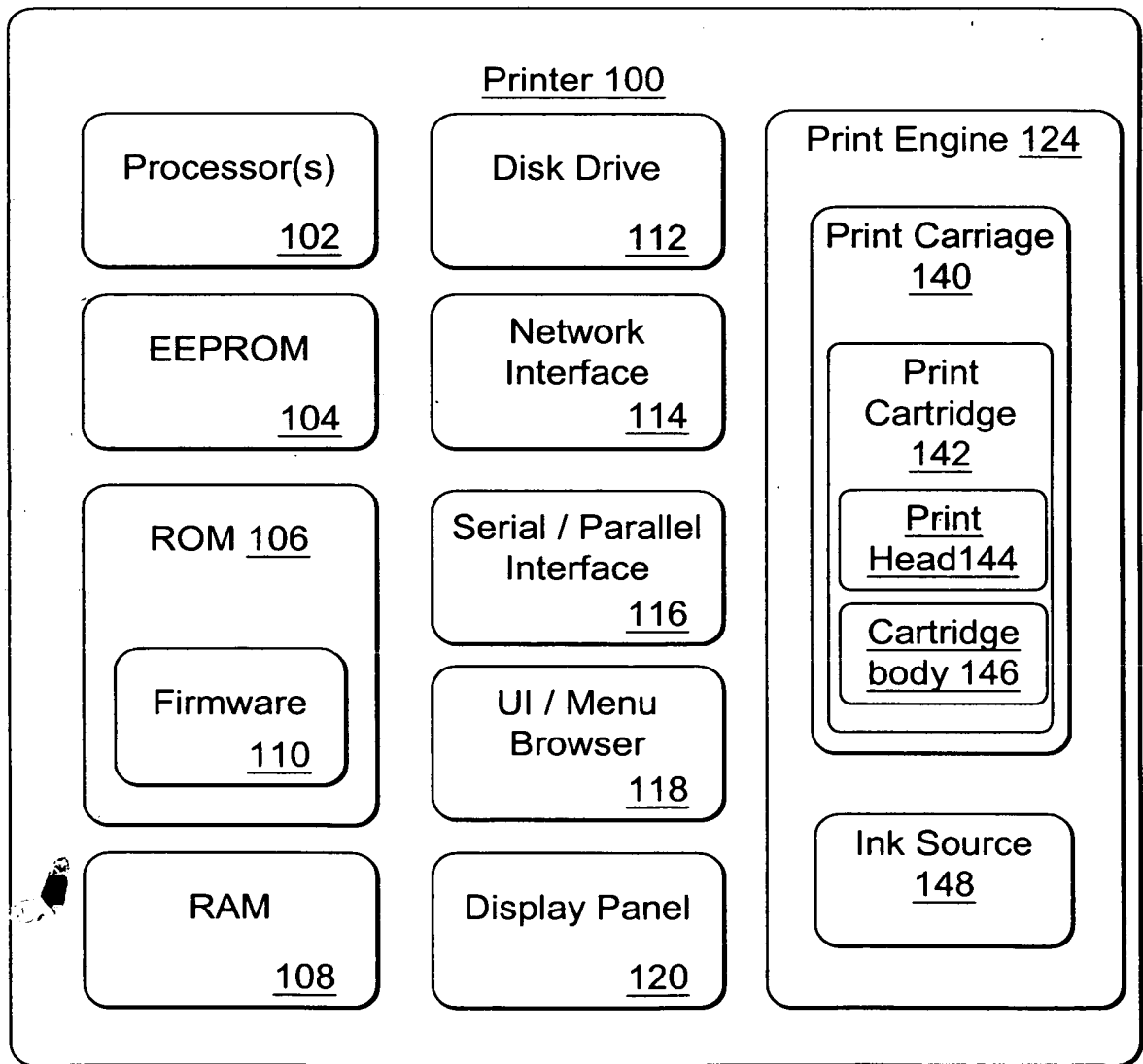


Fig. 2

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S/N: _____

Inventor: Shen Buswell et al
Title: Methods and systems for a forming slots in
a semiconductor substrate containing . . .

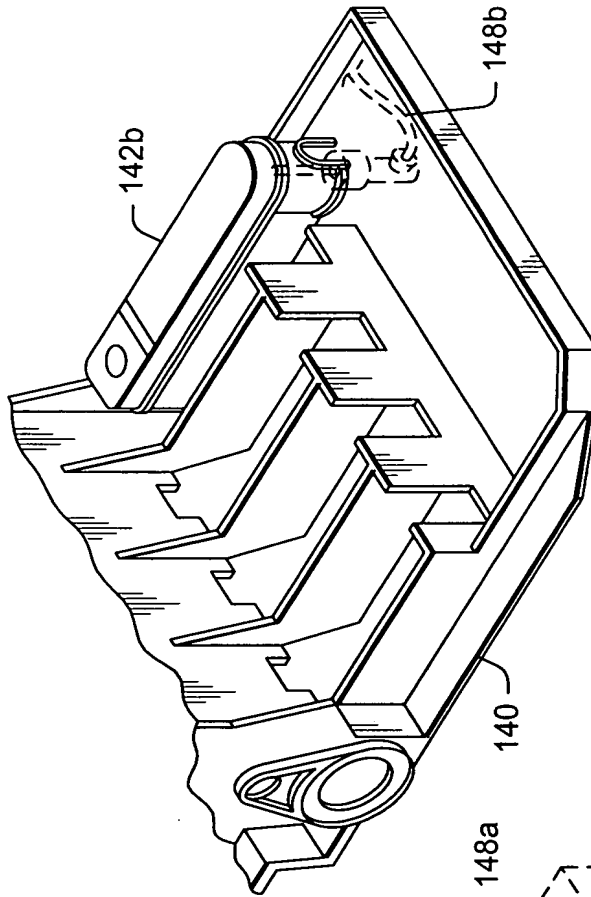


FIG. 3

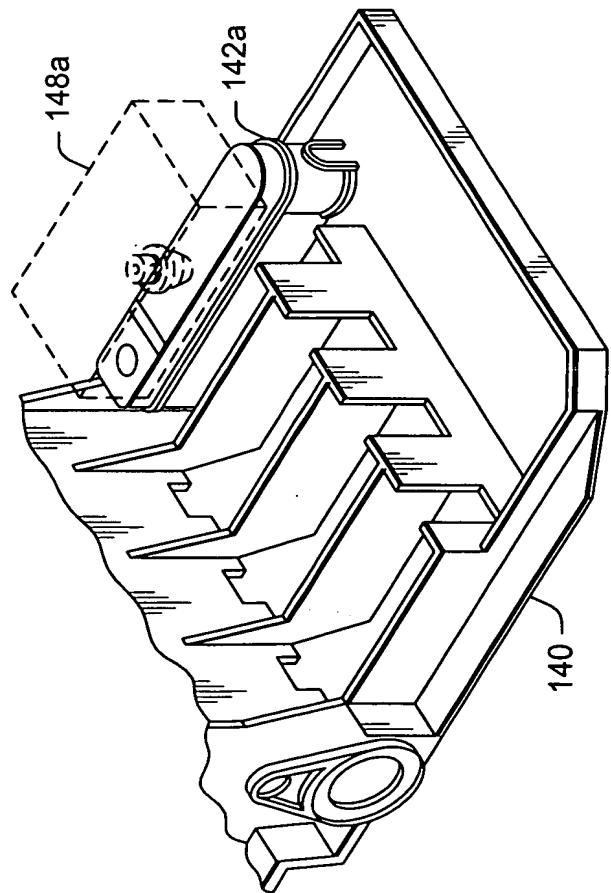


FIG. 4

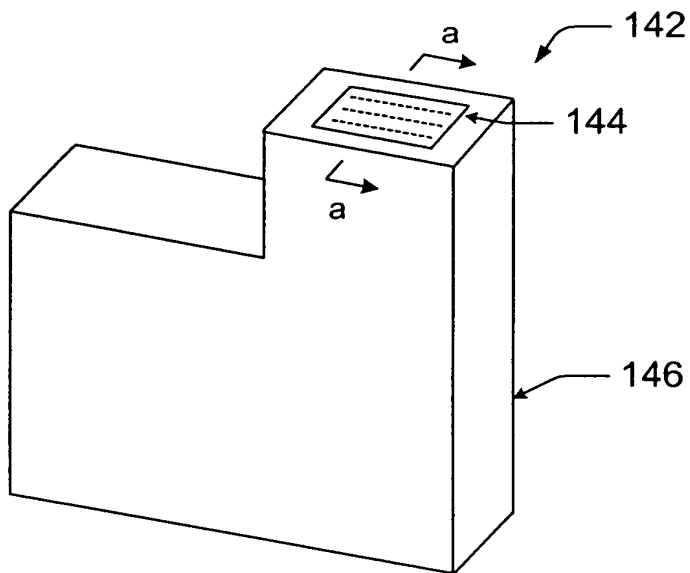


Fig. 5

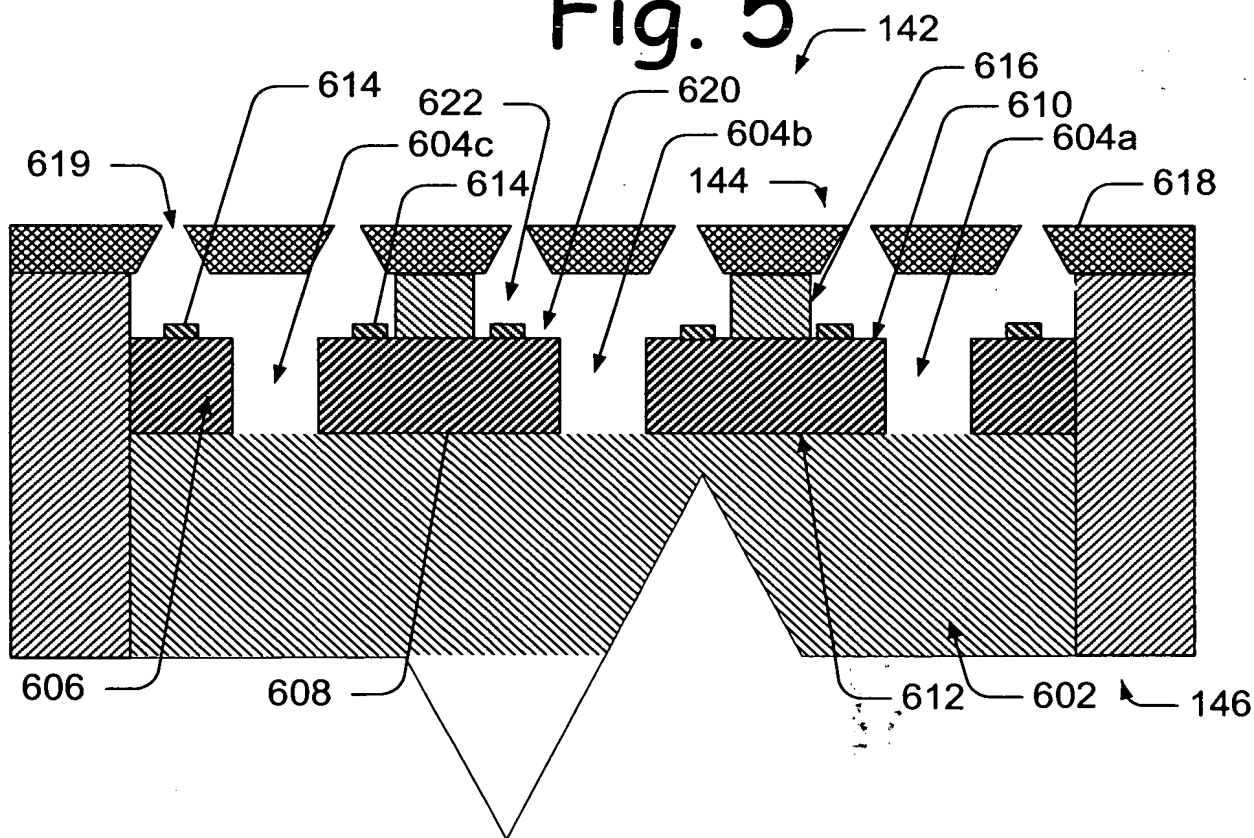


Fig. 6

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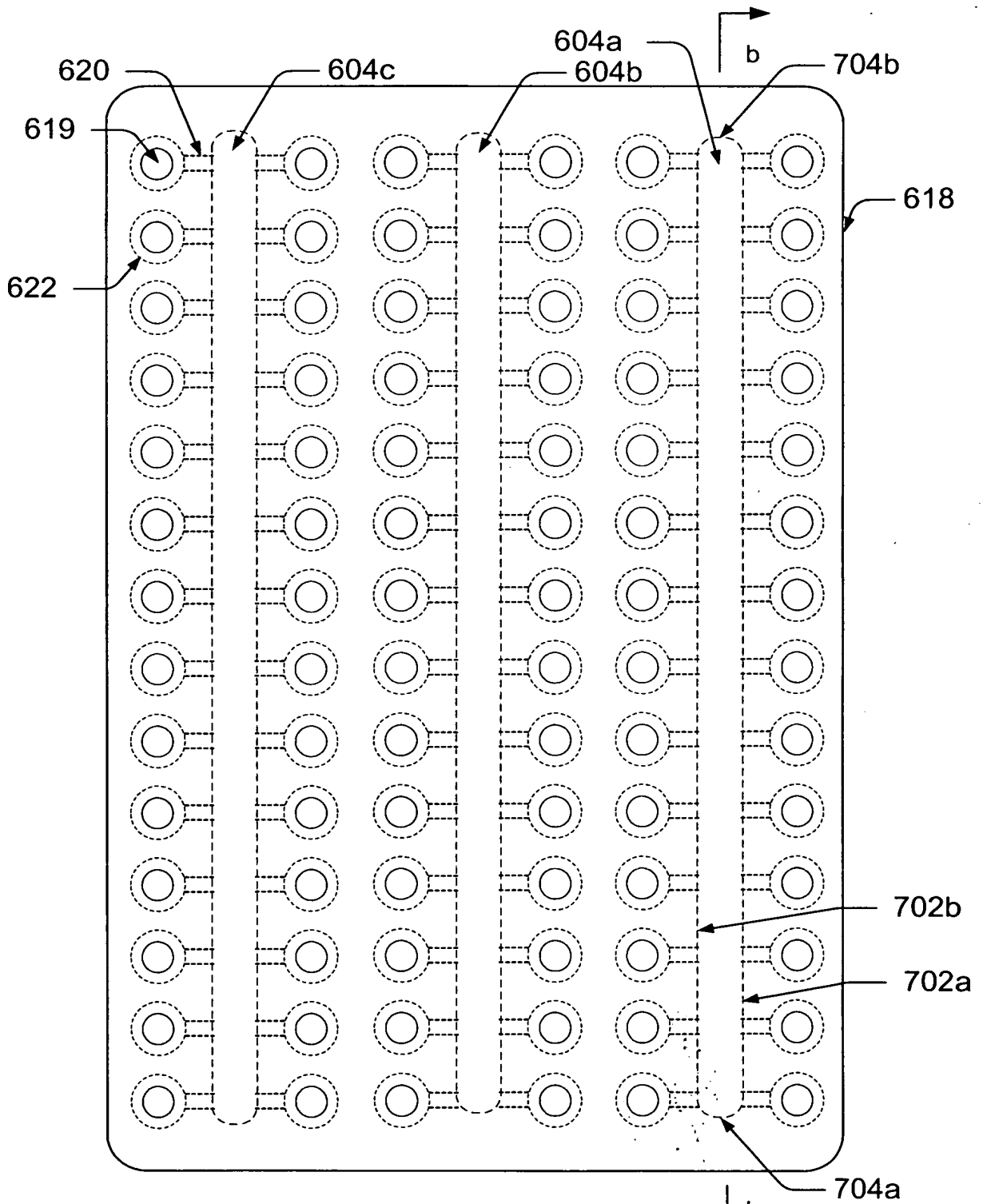


Fig. 7

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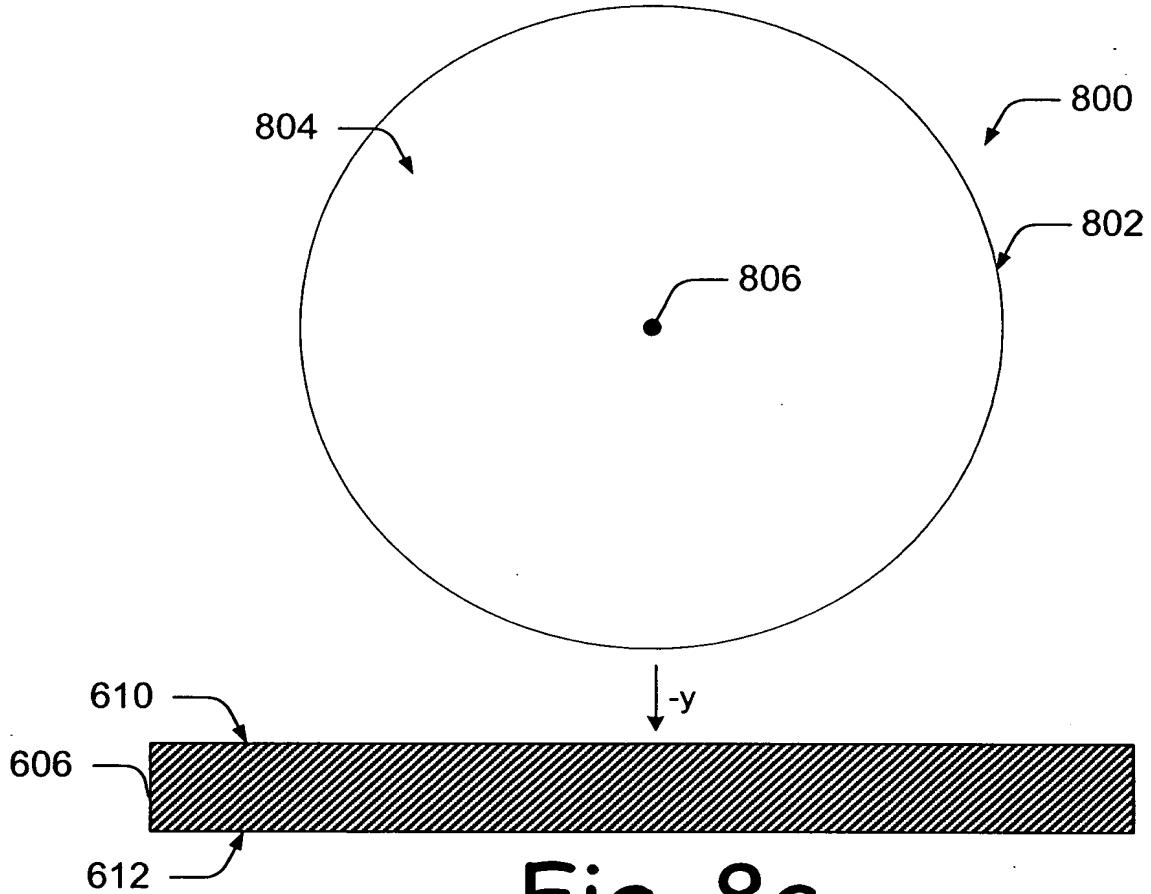


Fig. 8a

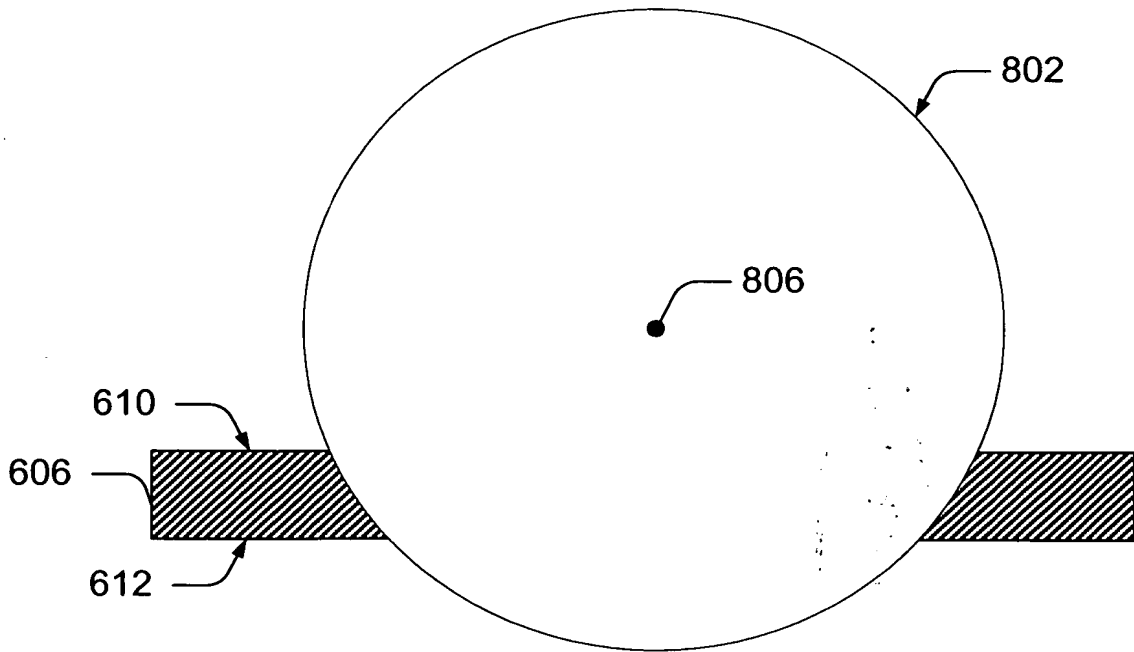


Fig. 8b

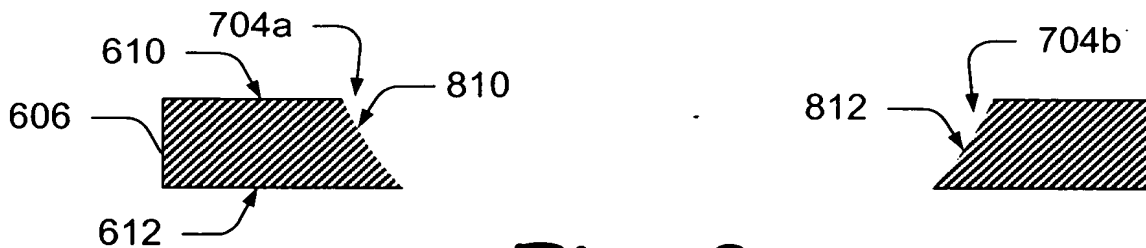


Fig. 8c

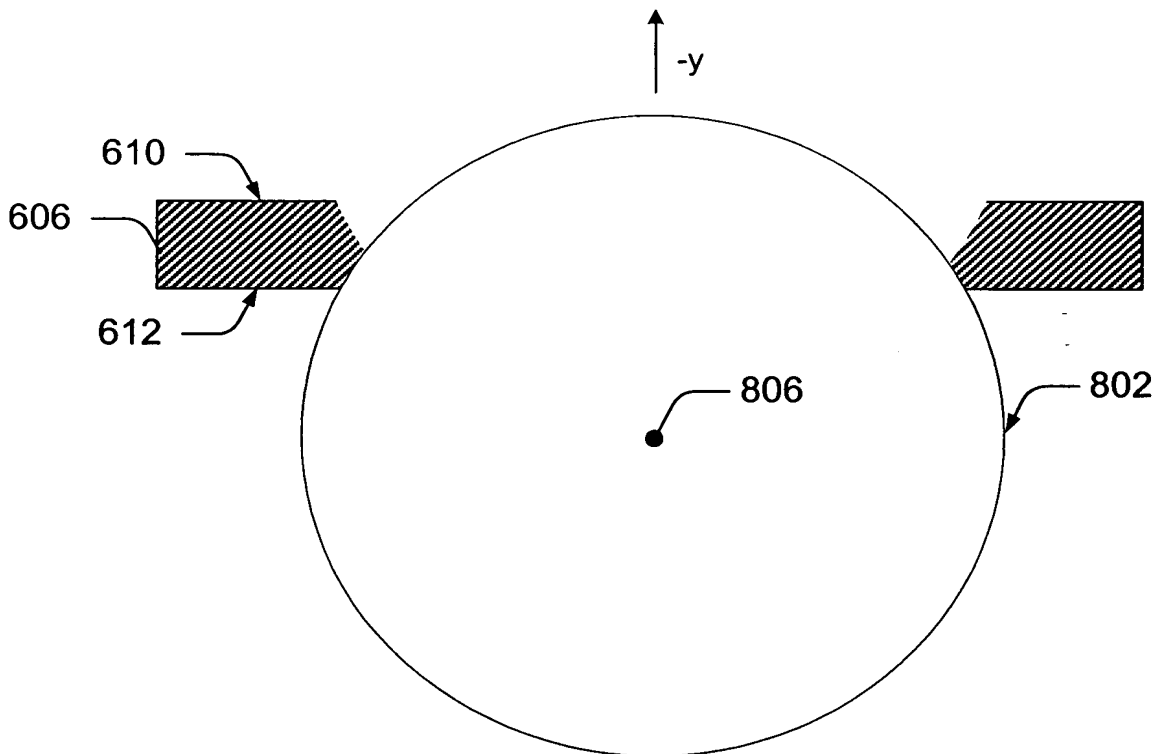


Fig. 8d

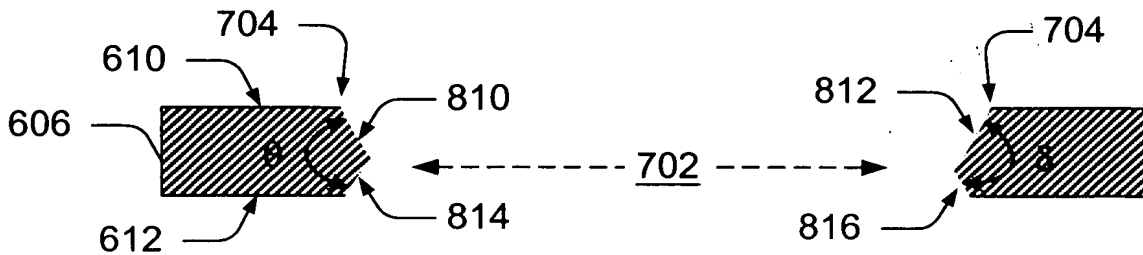
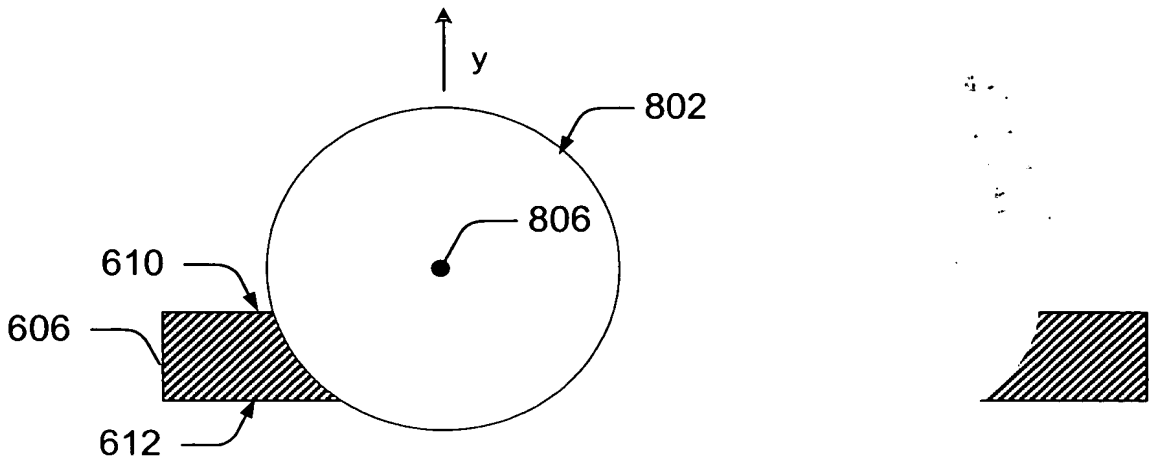
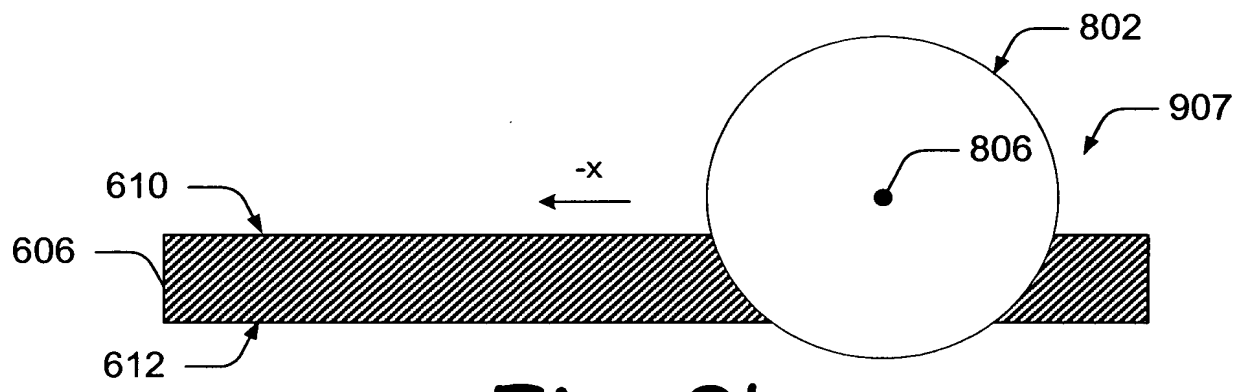
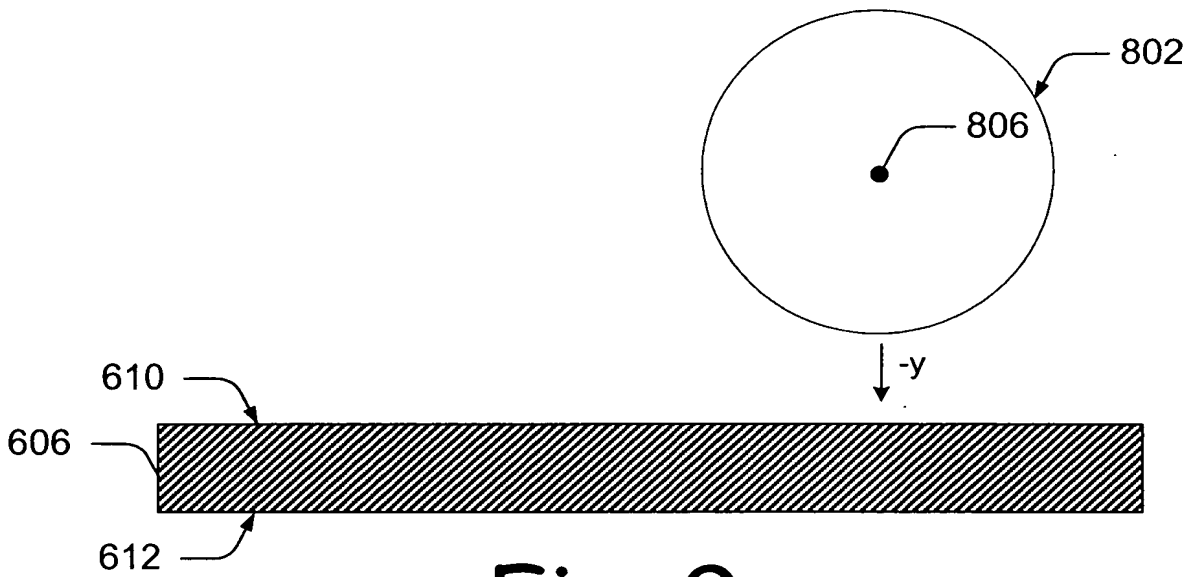


Fig. 8e

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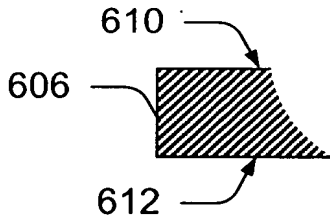


Fig. 9d

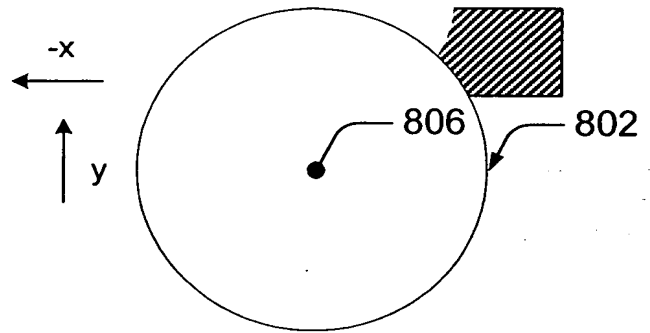
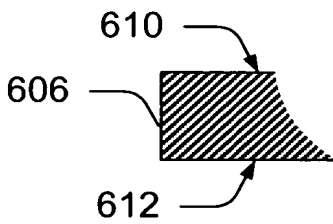


Fig. 9e

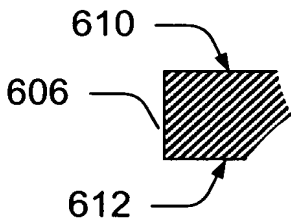


Fig. 9f

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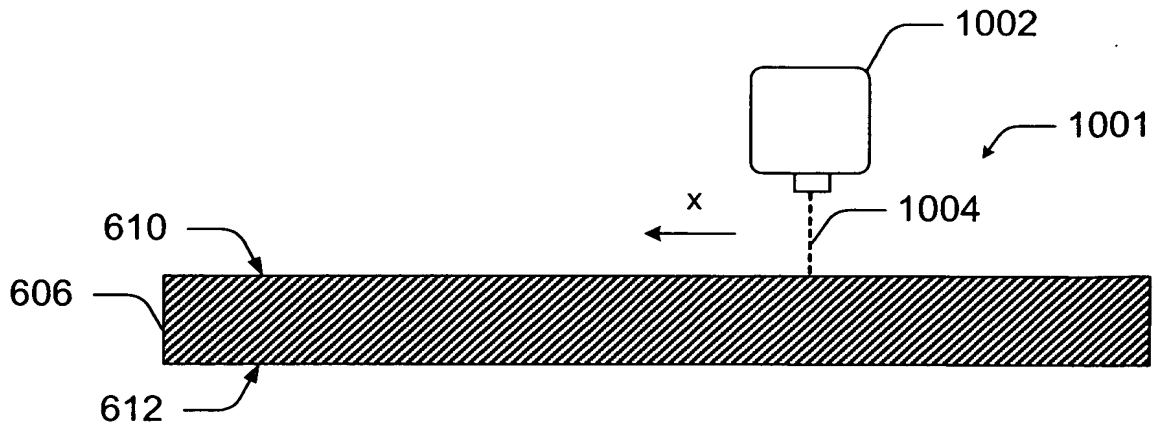


Fig. 10a

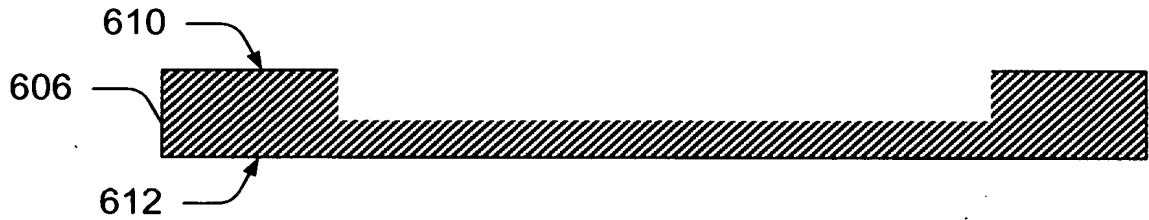


Fig. 10b

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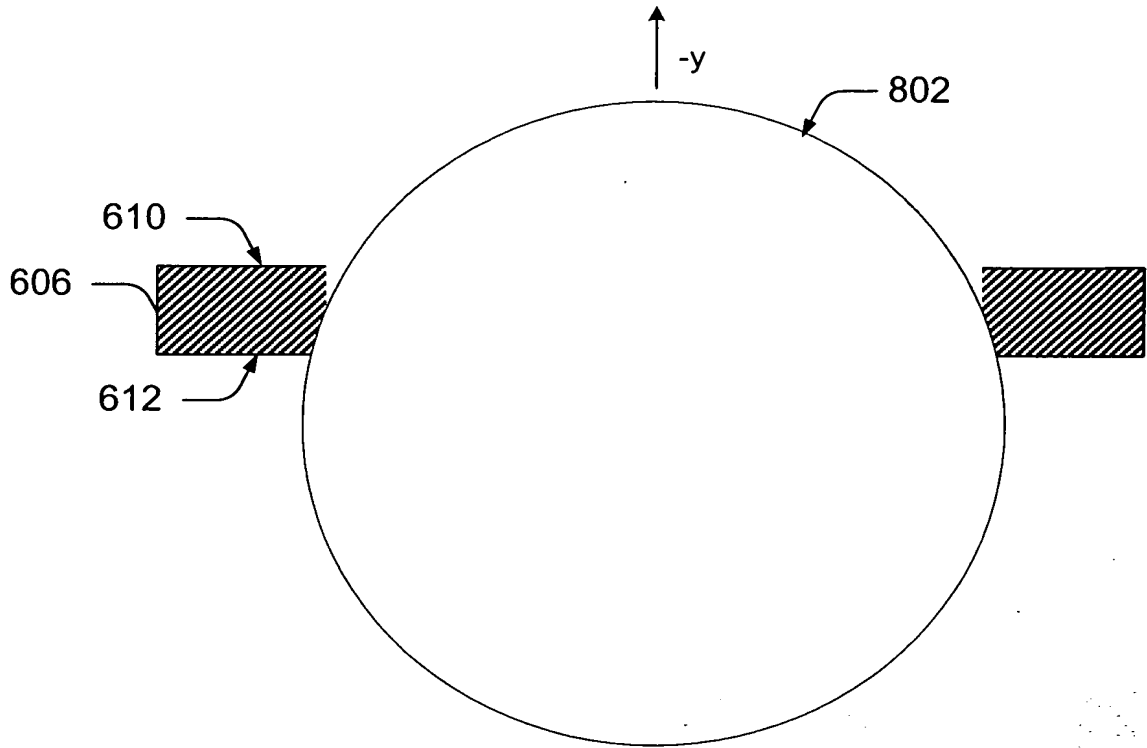


Fig. 10c



Fig. 10d

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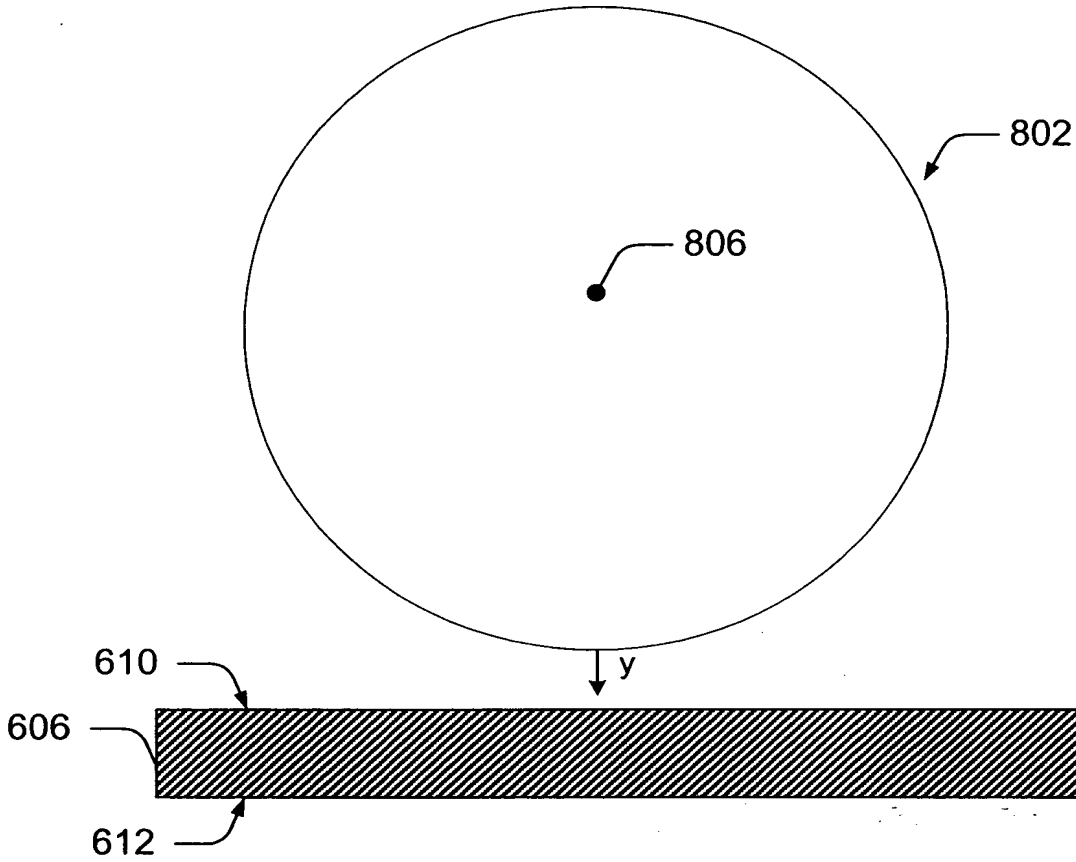


Fig. 11a

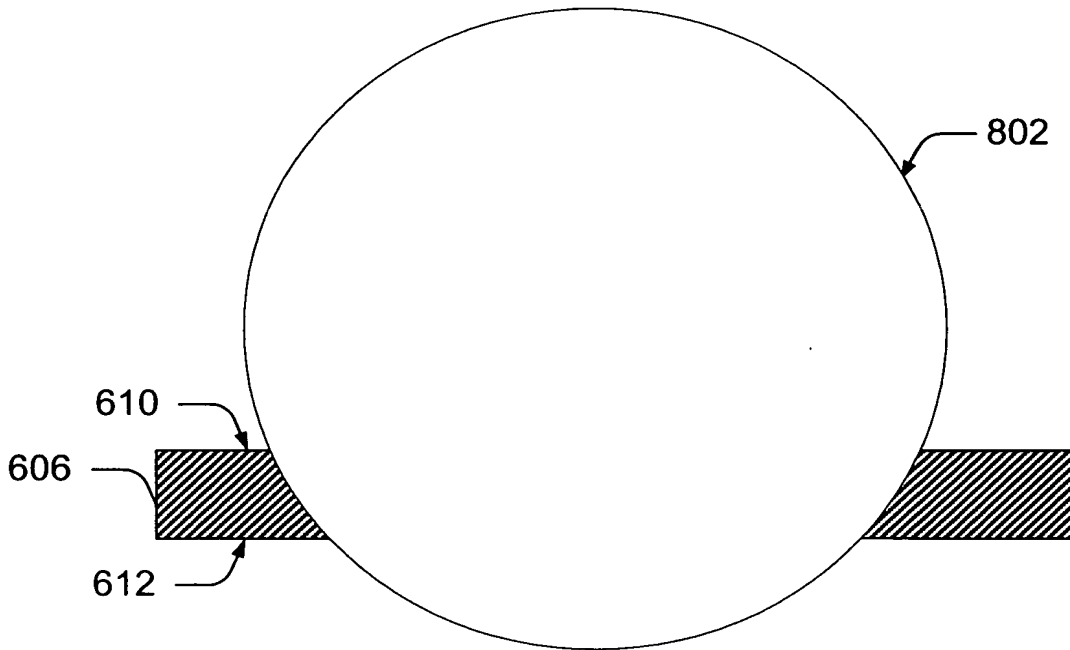


Fig. 11b

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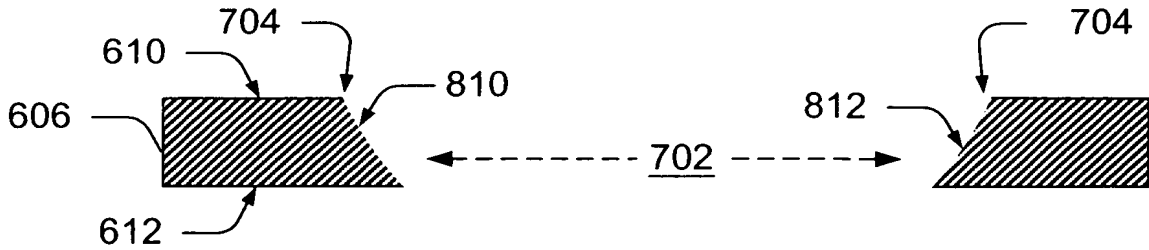


Fig. 11c

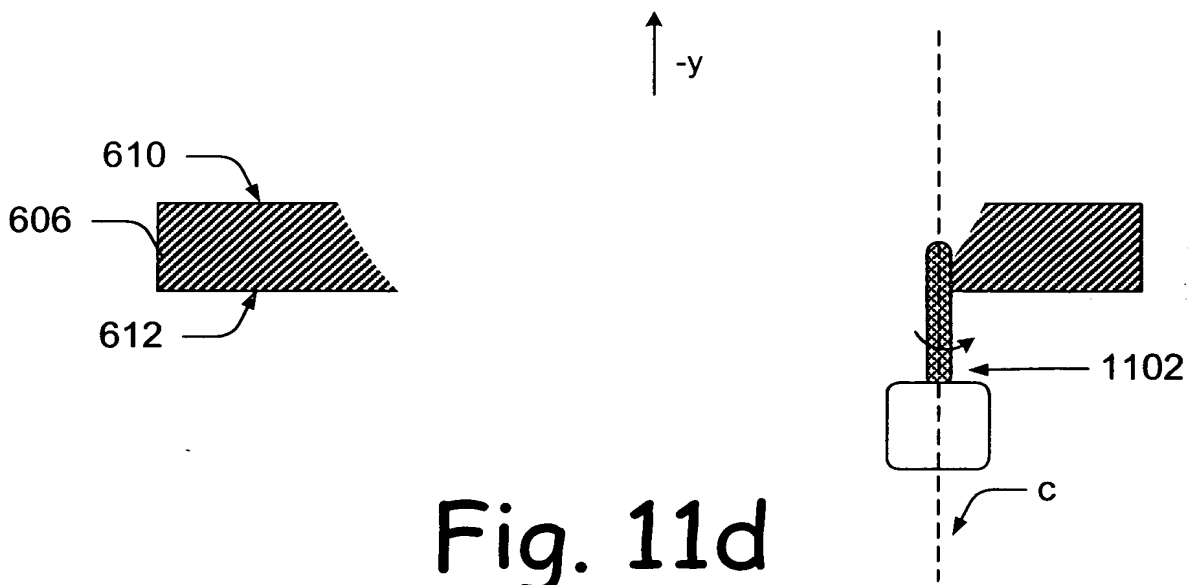


Fig. 11d

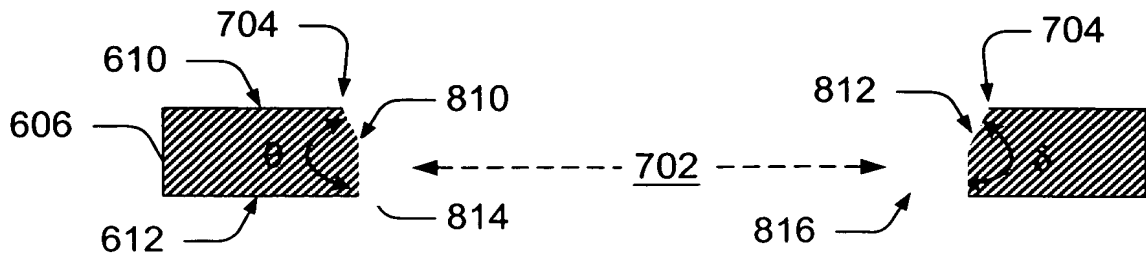


Fig. 11e

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